

IN THE SPECIFICATION

Please amend the following paragraphs as follows:

[0012] **Figure 1** is a schematic top side view of a portion of a substrate such as a wafer with number of discrete circuit structures formed therein and thereon. **Figure 2** is a cross-sectional side view of the structure of **Figure 1** through line A-A'. Referring to **Figure 1** and **Figure 2**, structure 100 includes substrate 105 of, for example, a semiconductor material such as silicon or a semiconductor layer on an insulator such as glass. Structure 100 is a portion of a structure at a wafer level with a number of circuit structures (dies or chips) discretely represented and connected at this point. Each circuit structure (e.g., die or chip 110A, . . . 110I) is separated on substrate 105 by scribe streets 120 that are used as a singulation area to separate the circuit structures from the substrate into a discrete die or chip. **Figure 1** shows dies or chips 110A, 110B, 110C, 110D, 110E, 110F, 110G, 110H, and 110I (see **Figure 1**). Each circuit structure (e.g., die or chip 110A, . . . 110I) may have a number of circuit devices formed in and on substrate 105 and one or more interconnection layers formed above substrate 105 and connecting with the devices on a respective die or chip. A top surface of each circuit structure may have a number of contact points including, in this example, solder or similar conductive material bumps to send or receive signals external to the die or chip. Bumps 115 protrude from a surface of a respective die or chip and, as viewed in **Figure 2**, are exposed on the surface of the respective die or chip. As shown in **Figure 2**, each bump protrudes from a surface of the substrate, a height, T_1 of, on the order of 75 microns. Each bump 115 may be surrounded by a dielectric material that otherwise covers the surface of substrate ~~100~~105.

[0013] **Figure 3A** shows the structure of **Figure 2** following the introduction of a chemically soluble coating on a surface of structure 100. Chemically soluble coating 130 is deposited, in one embodiment, to a thickness, T_2 , that is greater than a height, T_1 , of protrusion of bumps 115 from a surface of the substrate. In this manner, chemically soluble coating 130 overlies (as viewed) bumps 115. In another embodiment, shown in **Figure 3B**, chemically soluble coating 130 is deposited as a relatively conformal coating, conforming to the surface of structure 100 and overlying bumps 115. A representative thickness of chemically soluble coating 130 is on the order of five to 35 microns (μm) and, in this embodiment, is thick enough to ~~overly~~

overlie bumps 115 but not too thick that chemically soluble coating 130 may be not be subsequently removed in a reasonable time. Chemically soluble coating 130, as viewed, overlies each circuit structure of structure ~~110~~100 as well as scribe streets 120.